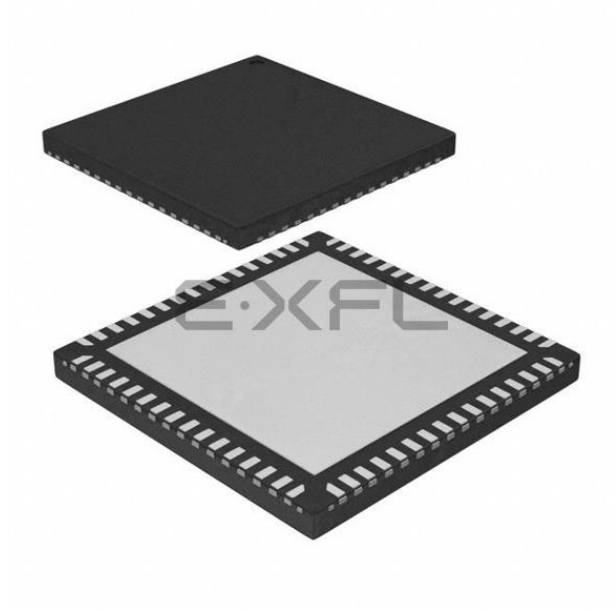

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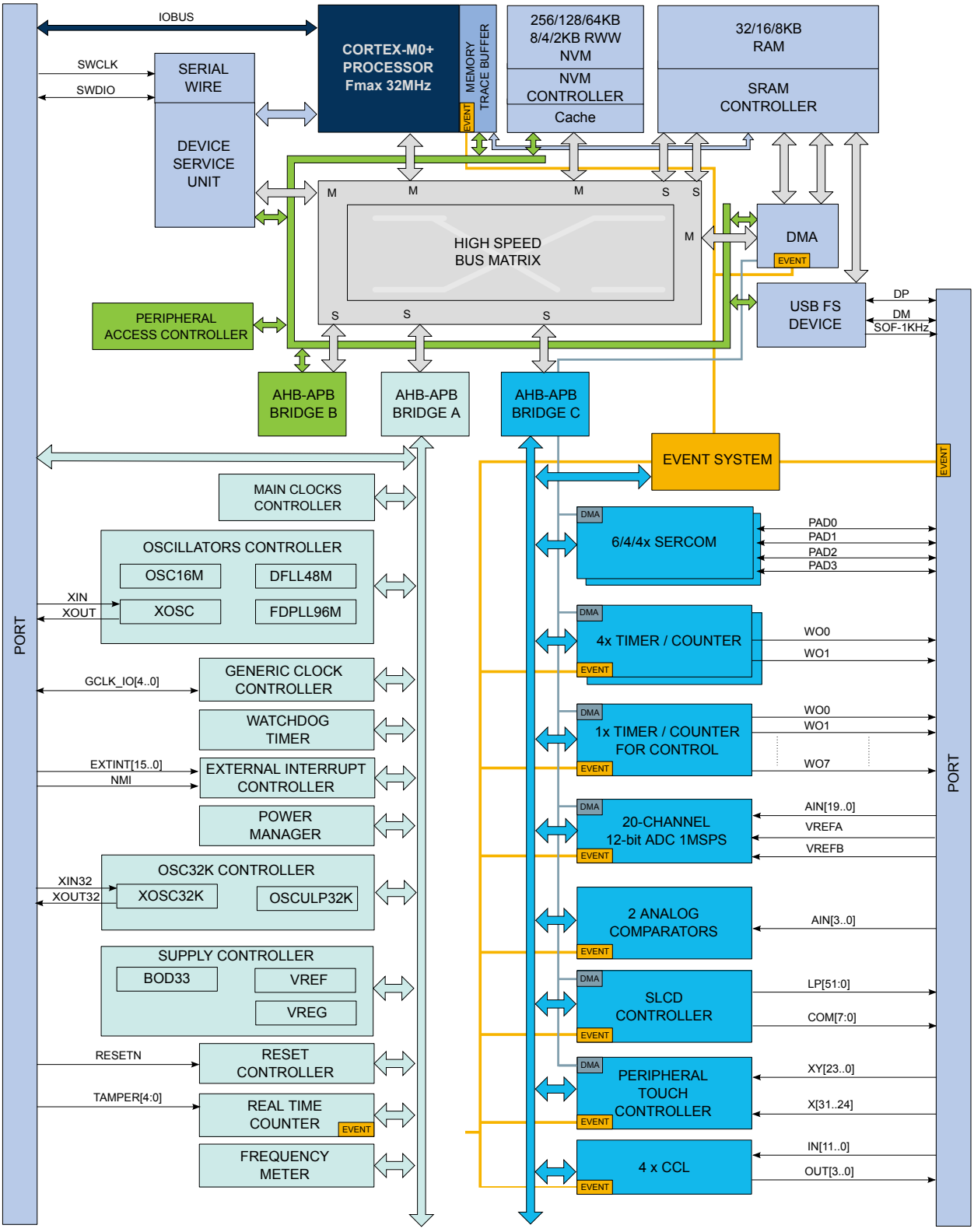
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.63V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsaml22j17a-mut

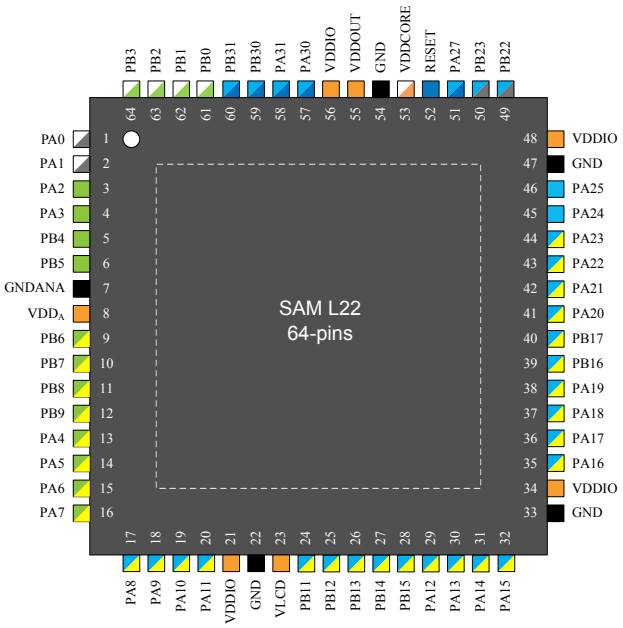
Table of Contents

4. Block Diagram

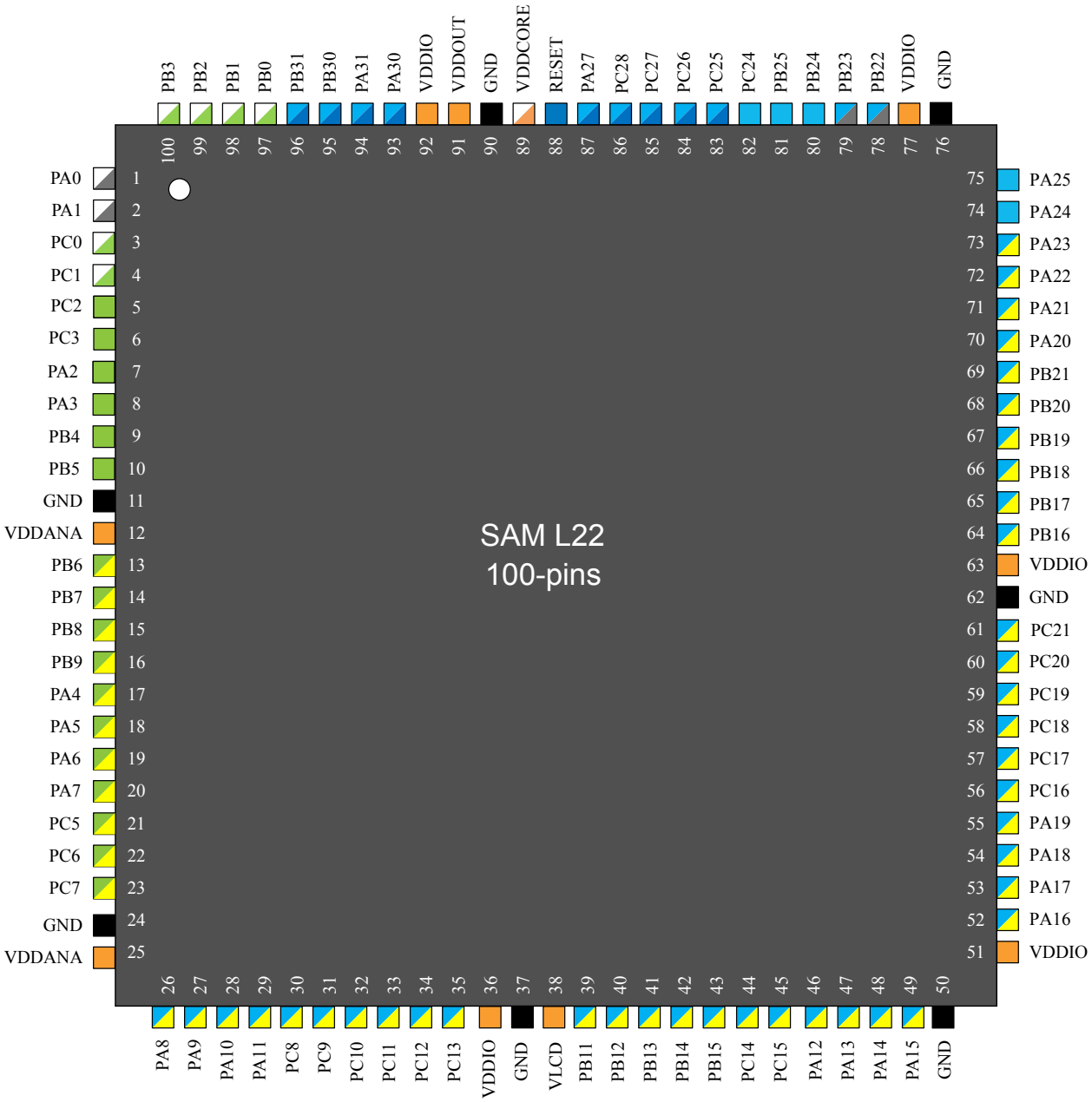


Note:

5.2. SAM L22J


SAM L22
64-pins
PB3 64
PB2 63
PB1 62
PB0 61
PB31 60
PB30 59
PA31 58
PA30 57
VDDIO 56
VDDOUT 55
GND 54
VDDCORE 53
RESET 52
PA27 51
PB23 50
PB22 49
PA0 1
PA1 2
PA2 3
PA3 4
PB4 5
PB5 6
GNDANA 7
VDDA 8
PB6 9
PB7 10
PB8 11
PB9 12
PA4 13
PA5 14
PA6 15
PA7 16
48 VDDIO
47 GND
46 PA25
45 PA24
44 PA23
43 PA22
42 PA21
41 PA20
40 PB17
39 PB16
38 PA19
37 PA18
36 PA17
35 PA16
34 VDDIO
33 GND
17 PA8
18 PA9
19 PA10
20 PA11
21 VDDIO
22 GND
23 VLCD
24 PB11
25 PB12
26 PB13
27 PB14
28 PB15
29 PA12
30 PA13
31 PA14
32 PA15

5.3. SAM L22N


SAM L22
100-pins
PB3 100
PB2 99
PB1 98
PB0 97
PB31 96
PB30 95
PA31 94
PA30 93
VDDIO 92
VDDOUT 91
GND 90
VDDCORE 89
RESET 88
PA27 87
PC28 86
PC27 85
PC26 84
PC25 83
PC24 82
PB25 81
PB24 80
PB23 79
PB22 78
VDDIO 77
GND 76
PA0 1
PA1 2
PC0 3
PC1 4
PC2 5
PC3 6
PA2 7
PA3 8
PB4 9
PB5 10
GND 11
VDDANA 12
PB6 13
PB7 14
PB8 15
PB9 16
PA4 17
PA5 18
PA6 19
PA7 20
PC5 21
PC6 22
PC7 23
GND 24
VDDANA 25
75 PA25
74 PA24
73 PA23
72 PA22
71 PA21
70 PA20
69 PB21
68 PB20
67 PB19
66 PB18
65 PB17
64 PB16
63 VDDIO
62 GND
61 PC21
60 PC20
59 PC19
58 PC18
57 PC17
56 PC16
55 PA19
54 PA18
53 PA17
52 PA16
51 VDDIO
26 PA8
27 PA9
28 PA10
29 PA11
30 PC8
31 PC9
32 PC10
33 PC11
34 PC12
35 PC13
36 VDDIO
37 GND
38 VLCD
39 PB11
40 PB12
41 PB13
42 PB14
43 PB15
44 PC14
45 PC15
46 PA12
47 PA13
48 PA14
49 PA15
50 GND

6. Signal Descriptions List

The following table gives details on signal names classified by peripheral.

Table 6-1. Signal Descriptions List

Signal Name	Function	Type	Active Level
Analog Comparators - AC			
AIN[3:0]	AC Analog Inputs	Analog	
CMP[1:0]	AC Analog Output	Analog	
Analog Digital Converter - ADC			
AIN[19:0]	ADC Analog Inputs	Analog	
VREFA	ADC Voltage External Reference A	Analog	
VREFB	ADC Voltage External Reference B	Analog	
External Interrupt Controller - EIC			
EXTINT[15:0]	External Interrupts inputs	Digital	
NMI	External Non-Maskable Interrupt input	Digital	
Generic Clock Generator - GCLK			
GCLK_IO[4:0]	Generic Clock (source clock inputs or generic clock generator output)	Digital	
Custom Control Logic - CCL			
IN[11:0]	Logic Inputs	Digital	
OUT[3:0]	Logic Outputs	Digital	
Supply Controller - SUPC			
VBAT	External battery supply Inputs	Analog	
PSOK	Main Power Supply OK input	Digital	
OUT[1:0]	Logic Outputs	Digital	
Power Manager - PM			
RESETN	Reset input	Digital	Low
Serial Communication Interface - SERCOMx			
PAD[3:0]	SERCOM Inputs/Outputs Pads	Digital	
Oscillators Control - OSCCTRL			
XIN	Crystal or external clock Input	Analog/Digital	
XOUT	Crystal Output	Analog	

Signal Name	Function	Type	Active Level
SOF 1kHz	USB Start of Frame	Digital	
Real Timer Clock - RTC			
RTC_IN[4:0]	Tamper or external wake-up pins	Digital	
RTC_OUT	Tamper output	Digital	

Table 7-2. Oscillator Pinout

Oscillator	Supply	Signal	I/O pin
XOSC	VDDIO	XIN	PB22
		XOUT	PB23
XOSC32K	VSWOUT	XIN32	PA00
		XOUT32	PA01

Note: In order to minimize the cycle-to-cycle jitter of the external oscillator, keep the neighboring pins as steady as possible. For neighboring pin details, refer to the Oscillator Pinout section.

Table 7-3. XOSC32K Jitter Minimization

Package	Steady Signal Recommended
L22N	PB00, PB01, PB02, PB03, PC00, PC01
L22J	PB00, PB01, PB02, PB03, PA02, PA03
L22G	PB02, PB03, PA02, PA03

7.2.2. Serial Wire Debug Interface Pinout

Only the SWCLK pin is mapped to the normal PORT functions. A debugger cold-plugging or hot-plugging detection will automatically switch the SWDIO port to the SWDIO function.

Table 7-4. Serial Wire Debug Interface Pinout

Signal	Supply	I/O pin
SWCLK	VDDIO	PA30
SWDIO	VDDIO	PA31

7.2.3. SERCOM USART and I²C Configurations

The SAM L22 has up to six instances of the serial communication interface (SERCOM) peripheral. The following table lists the supported communication protocols for each SERCOM instance.

Table 7-5. SERCOM USART and I²C Protocols

	SERCOM Instance					
Protocol	SERCOM0	SERCOM1	SERCOM2	SERCOM3	SERCOM4	SERCOM5
I²C	no	yes	yes	yes	yes	yes
I²C at 3.4MHz	no	yes	no	no	no	yes
USART including RS485 and ISO 7816	yes	yes	yes	yes	yes	yes
SPI	yes	yes	yes	yes	yes	yes

Note: Not all available I²C pins support I²C mode at 3.4MHz.

Figure 8-2. Power Supply Connection for Switching/Linear Mode

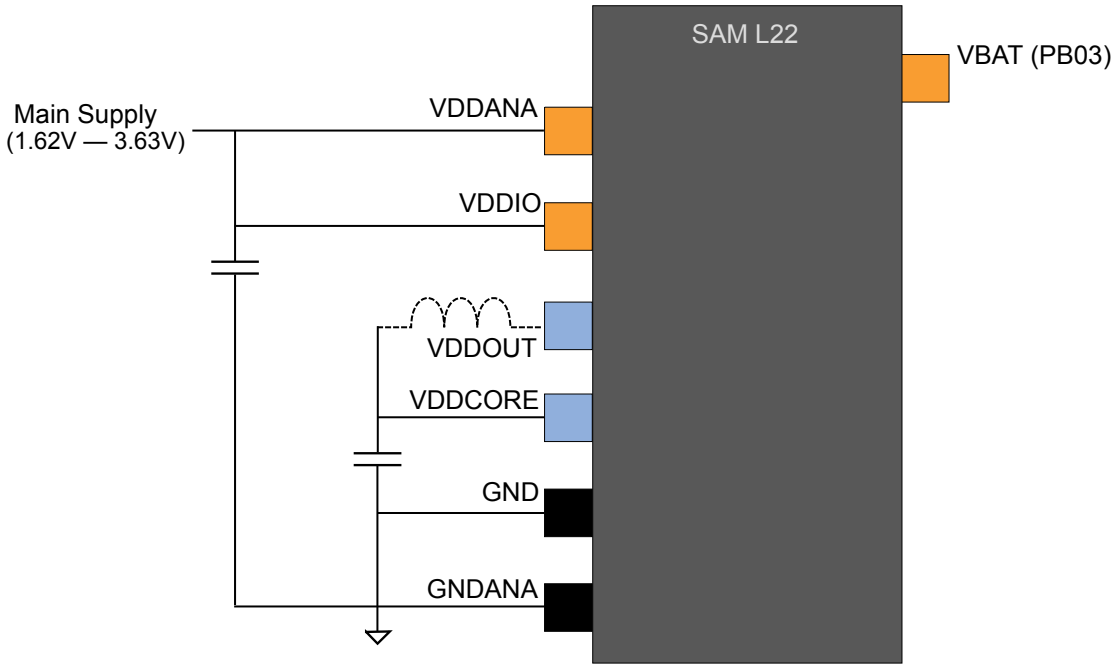
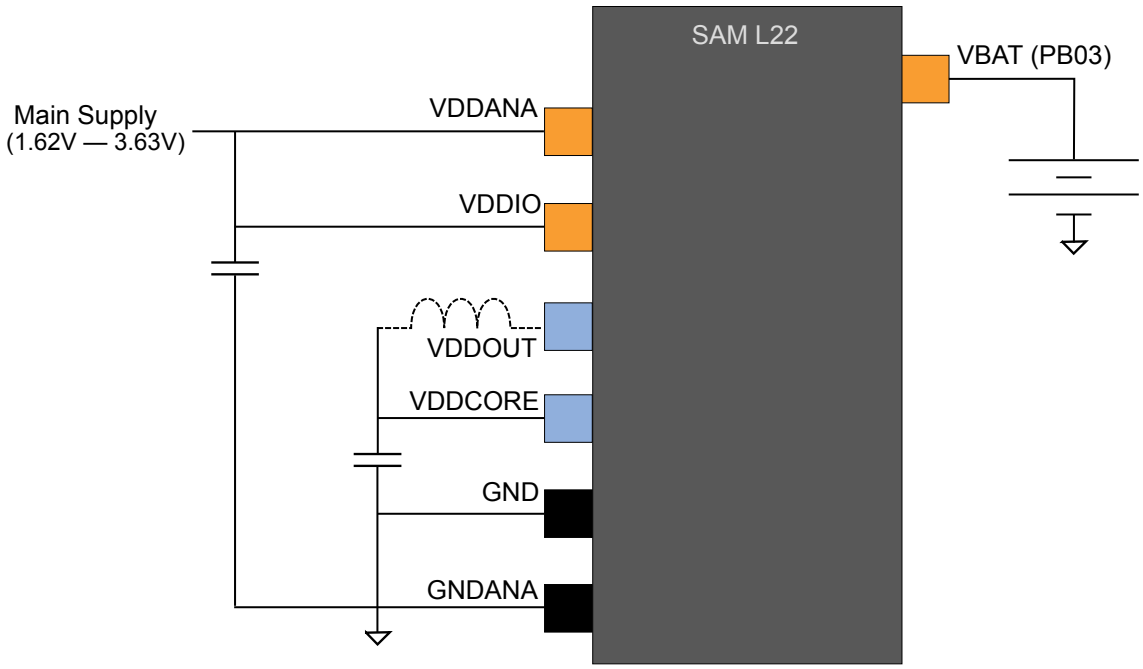


Figure 8-3. Power Supply Connection for Battery Backup



8.2.4. Power-Up Sequence

8.2.4.1. Supply Order

VDDIO and VDDANA must have the same supply sequence. Ideally, they must be connected together.

8.2.4.2. Minimum Rise Rate

One integrated power-on reset (POR) circuits monitoring VDDIO requires a minimum rise rate.

8.2.4.3. Maximum Rise Rate

The rise rate of the power supplies must not exceed the values described in Electrical Characteristics.

8.3. Power-Up

This section summarizes the power-up sequence of the SAM L22. The behavior after power-up is controlled by the Power Manager.

8.3.1. Starting of Internal Regulator

After power-up, the device is set to its initial state and kept in Reset, until the power has stabilized throughout the device. The default performance level after power-up is PL0.

The internal regulator provides the internal VDDCORE corresponding to this performance level. Once the external voltage VDDIO and the internal VDDCORE reach a stable value, the internal Reset is released.

8.3.2. Starting of Clocks

Once the power has stabilized and the internal Reset is released, the device will use a 4MHz clock by default. The clock source for this clock signal is OSC16M, which is enabled and configured at 4MHz after a reset by default. This is also the default time base for Generic Clock Generator 0. In turn, Generator 0 provides the main clock GCLK_MAIN which is used by the Power Manager (PM).

Some synchronous system clocks are active after Start-Up, allowing software execution. Refer to the “Clock Mask Register” section in the PM-Power Manager documentation for the list of clocks that are running by default. Synchronous system clocks that are running receive the 4MHz clock from Generic Clock Generator 0. Other generic clocks are disabled.

8.3.3. I/O Pins

After power-up, the I/O pins are tri-stated except PA30, which is pull-up enabled and configured as input.

8.3.4. Fetching of Initial Instructions

After Reset has been released, the CPU starts fetching PC and SP values from the Reset address, 0x00000000. This points to the first executable address in the internal Flash memory. The code read from the internal Flash can be used to configure the clock system and clock sources. See the related peripheral documentation for details. Refer to the ARM Architecture Reference Manual for more information on CPU startup (http://www.arm.com).

8.4. Power-On Reset and Brown-Out Detector

The SAM L22 embeds three features to monitor, warn and/or reset the device:

- POR: Power-on Reset on VSWOUT and VDDIO
- BOD33: Brown-out detector on VSWOUT/VBAT
- Brown-out detector internal to the voltage regulator for VDDCORE. BOD12 is calibrated in production and its calibration parameters are stored in the NVM User Row. This data should not be changed if the User Row is written to in order to assure correct behavior.

8.4.1. Power-On Reset on VSWOUT

VSWOUT is monitored by POR. Monitoring is always activated, including startup and all sleep modes. If VSWOUT goes below the threshold voltage, the entire chip is reset.

8.4.2. Power-On Reset on VDDIO

VDDIO is monitored by POR. Monitoring is always activated, including startup and all sleep modes. If VDDIO goes below the threshold voltage, all I/Os supplied by VDDIO are reset.

8.4.3. Brown-Out Detector on VSWOUT/VBAT

BOD33 monitors VSWOUT or VBAT depending on configuration.

8.4.4. Brown-Out Detector on VDDCORE

Once the device has started up, BOD12 monitors the internal VDDCORE.

8.5. Performance Level Overview

By default, the device will start in Performance Level 0. This PL0 is aiming for the lowest power consumption by limiting logic speeds and the CPU frequency. As a consequence, all GCLK will have limited capabilities, and some peripherals and clock sources will not work or with limited capabilities:

List of peripherals/clock sources not available in PL0:

- USB (limited by logic frequency)
- DFLL48M

List of peripherals/clock sources with limited capabilities in PL0:

- All AHB/APB peripherals are limited by CPU frequency
- DPLL96M: may be able to generate 48MHz internally, but the output cannot be used by logic
- GCLK: the maximum frequency is by factor 4 compared to PL2
- SW interface: the maximum frequency is by factor 4 compared to PL2
- TC: the maximum frequency is by factor 4 compared to PL2
- TCC:the maximum frequency is by factor 4 compared to PL2
- SERCOM: the maximum frequency is by factor 4 compared to PL2

List of peripherals/clock sources with full capabilities in PL0:

- AC
- ADC
- EIC
- OSC16M
- PTC
- All 32KHz clock sources and peripherals

Full functionality and capability will be ensured in PL2. When transitioning between performance levels, the Supply Controller (SUPC) will provide a configurable smooth voltage scaling transition.

10.3. NVM User Row Mapping

The Non Volatile Memory (NVM) User Row contains calibration data that are automatically read at device power-on.

The NVM User Row can be read at address 0x00804000.

To write the NVM User Row refer to the documentation of the NVMCTRL - Non-Volatile Memory Controller.

Note: When writing to the User Row, the new values do not get loaded by the other peripherals on the device until a device Reset occurs.

Table 10-4. NVM User Row Mapping

Bit Pos.	Name	Usage	Factory Setting	Related Peripheral Register
2:0	BOOTPROT	Used to select one of eight different bootloader sizes.	0x7	NVMCTRL
3	Reserved	—	0x1	—
6:4	EEPROM	Used to select one of eight different EEPROM sizes.	0x7	NVMCTRL
7	Reserved	—	0x1	—
13:8	BOD33 Level	BOD33 threshold level at power-on.	0x06	SUPC.BOD33
14	BOD33 Disable	BOD33 Disable at power-on.	0x0	SUPC.BOD33
16:15	BOD33 Action	BOD33 Action at power-on.	0x1	SUPC.BOD33
25:17	Reserved	Factory settings - do not change.	0x08F	-
26	WDT Enable	WDT Enable at power-on.	0x0	WDT.CTRLA
27	WDT Always-On	WDT Always-On at power-on.	0x0	WDT.CTRLA
31:28	WDT Period	WDT Period at power-on.	0xB	WDT.CONFIG
35:32	WDT Window	WDT Window mode time-out at power-on.	0xB	WDT.CONFIG
39:36	WDT EWOFFSET	WDT Early Warning Interrupt Time Offset at power-on.	0xB	WDT.EWCTRL
40	WDT WEN	WDT Timer Window Mode Enable at power-on.	0x0	WDT.CTRLA
41	BOD33 Hysteresis	BOD33 Hysteresis configuration at power-on.	0x0	SUPC.BOD33
47:42	Reserved	Factory settings - do not change.	0x3E	—
63:48	LOCK	NVM Region Lock Bits.	0xFFFF	NVMCTRL

11.2. Nested Vector Interrupt Controller

11.2.1. Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM L22 supports 32 interrupts with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (http://www.arm.com).

11.2.2. Interrupt Line Mapping

Each of the interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear (INTFLAG) register.

An interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a '1' to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing '1' to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register.

An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled.

The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR).

For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 11-3. Interrupt Line Mapping

Peripheral source	NVIC line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager MCLK - Main Clock OSCCTRL - Oscillators Controller OSC32KCTRL - 32KHz Oscillators Controller PAC - Peripheral Access Controller SUPC - Supply Controller	0
WDT – Watchdog Timer	1
RTC – Real Time Counter	2
EIC – External Interrupt Controller	3
FREQM - Frequency Meter	4
USB - Universal Serial Bus	5
NVMCTRL – Non-Volatile Memory Controller	6
DMAC - Direct Memory Access Controller	7

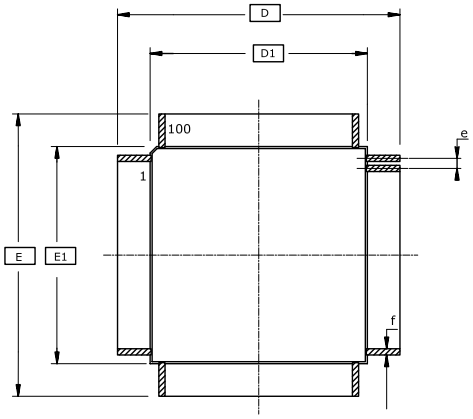
SRAM Port Connection	Port ID	Connection Type	QoS	default QoS
DMAC - Direct Memory Access Controller - Fetch Access	3, 4	Direct	IP-QOSCTRL.FQOS	0x2
DMAC - Direct Memory Access Controller - Write-Back Access	5, 6	Direct	IP-QOSCTRL.WRBQOS	0x2
USB - Universal Serial Bus	7	Direct	IP-QOSCTRL	0x3
MTB - Micro Trace Buffer	8	Direct	STATIC-3	0x3

Note: 1. Using 32-bit access only.

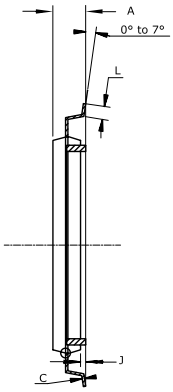
12.2. Package Drawings

12.2.1. 100 pin TQFP

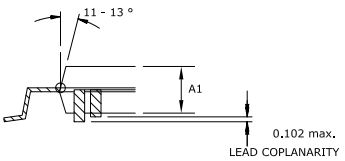
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW



DETAIL VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		16.00		
D1/E1		14.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		100		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

Table 12-2. Device and Package Maximum Weight

520	mg

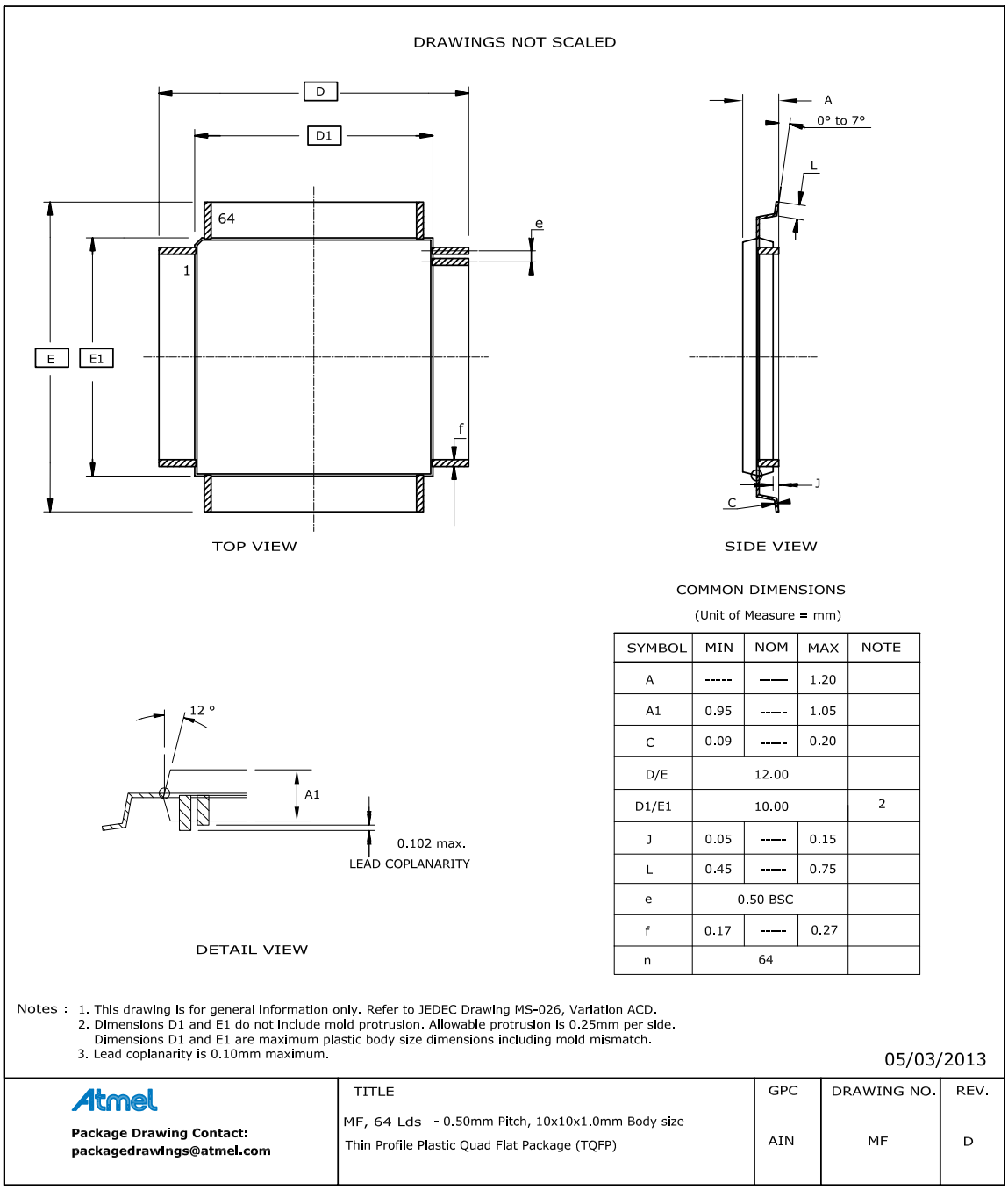
Table 12-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-4. Package Reference

JEDEC Drawing Reference	MS-026, variant AED
JESD97 Classification	e3

12.2.2. 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

Atmel	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

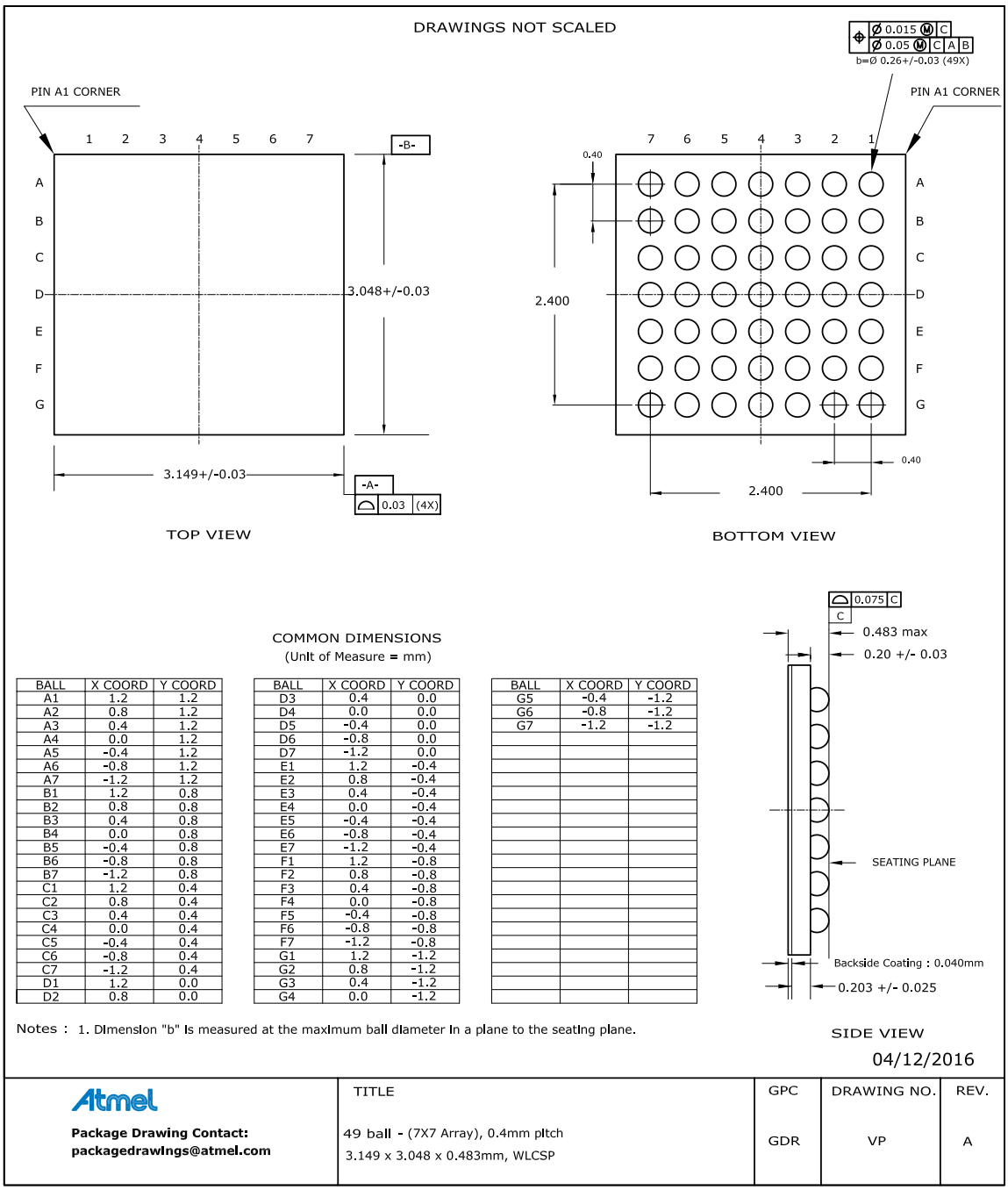
Table 12-5. Device and Package Maximum Weight

300	mg

Table 12-6. Package Characteristics

Moisture Sensitivity Level	MSL3

12.2.4. 49-Ball WLCSP



BALL	X COORD	Y COORD
A1	1.2	1.2
A2	0.8	1.2
A3	0.4	1.2
A4	0.0	1.2
A5	-0.4	1.2
A6	-0.8	1.2
A7	-1.2	1.2
B1	1.2	0.8
B2	0.8	0.8
B3	0.4	0.8
B4	0.0	0.8
B5	-0.4	0.8
B6	-0.8	0.8
B7	-1.2	0.8
C1	1.2	0.4
C2	0.8	0.4
C3	0.4	0.4
C4	0.0	0.4
C5	-0.4	0.4
C6	-0.8	0.4
C7	-1.2	0.4
D1	1.2	0.0
D2	0.8	0.0

BALL	X COORD	Y COORD
D3	0.4	0.0
D4	0.0	0.0
D5	-0.4	0.0
D6	-0.8	0.0
D7	-1.2	0.0
E1	1.2	-0.4
E2	0.8	-0.4
E3	0.4	-0.4
E4	0.0	-0.4
E5	-0.4	-0.4
E6	-0.8	-0.4
E7	-1.2	-0.4
F1	1.2	-0.8
F2	0.8	-0.8
F3	0.4	-0.8
F4	0.0	-0.8
F5	-0.4	-0.8
F6	-0.8	-0.8
F7	-1.2	-0.8
G1	1.2	-1.2
G2	0.8	-1.2
G3	0.4	-1.2
G4	0.0	-1.2

BALL	X COORD	Y COORD
G5	-0.4	-1.2
G6	-0.8	-1.2
G7	-1.2	-1.2

Table 12-11. Device and Package Maximum Weight

8.45	mg

Table 12-12. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 12-13. Package Reference

JEDEC Drawing Reference	N/A
JESD97 Classification	E1

12.2.5. 48 pin TQFP

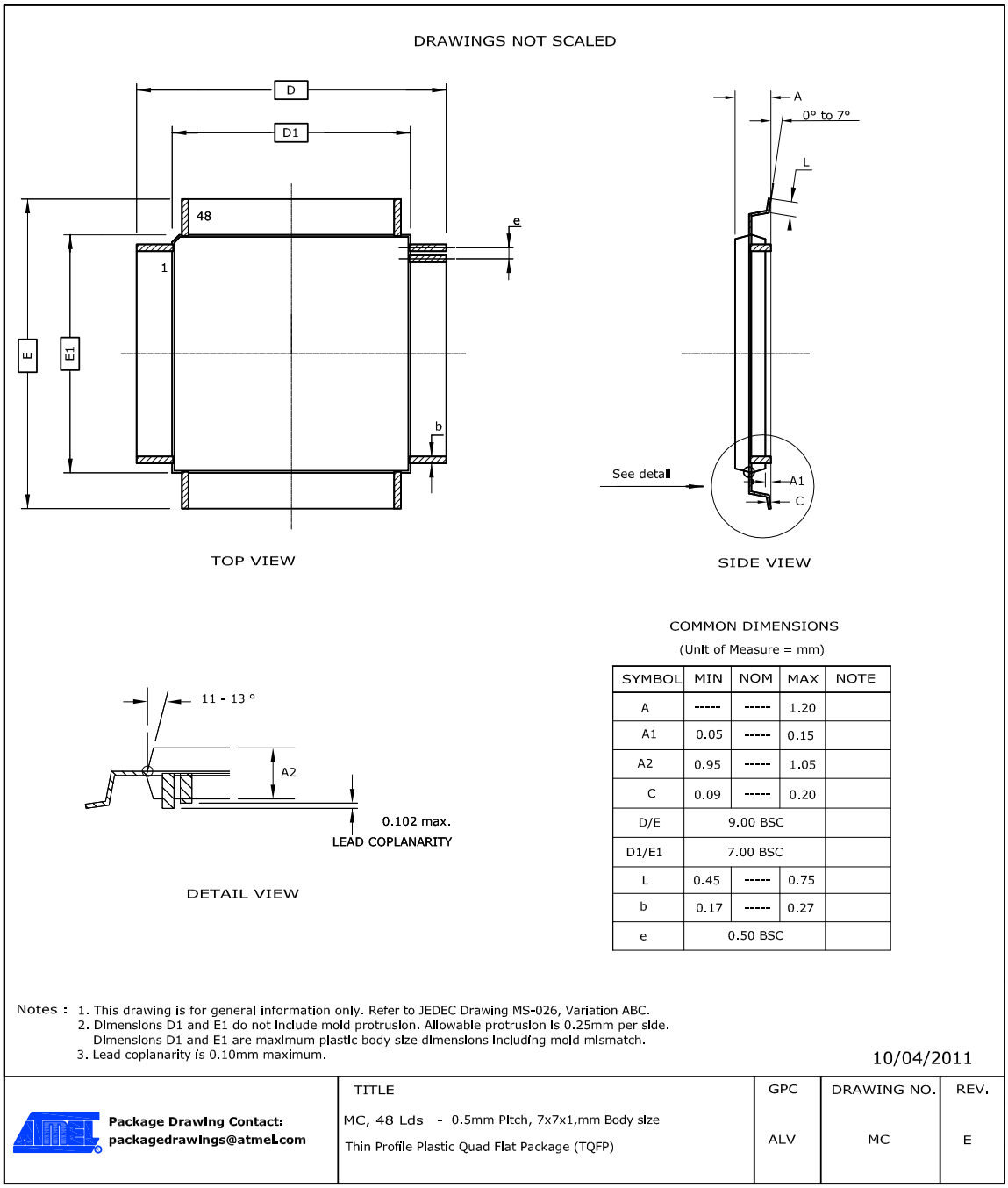


Table 12-14. Device and Package Maximum Weight

140	mg

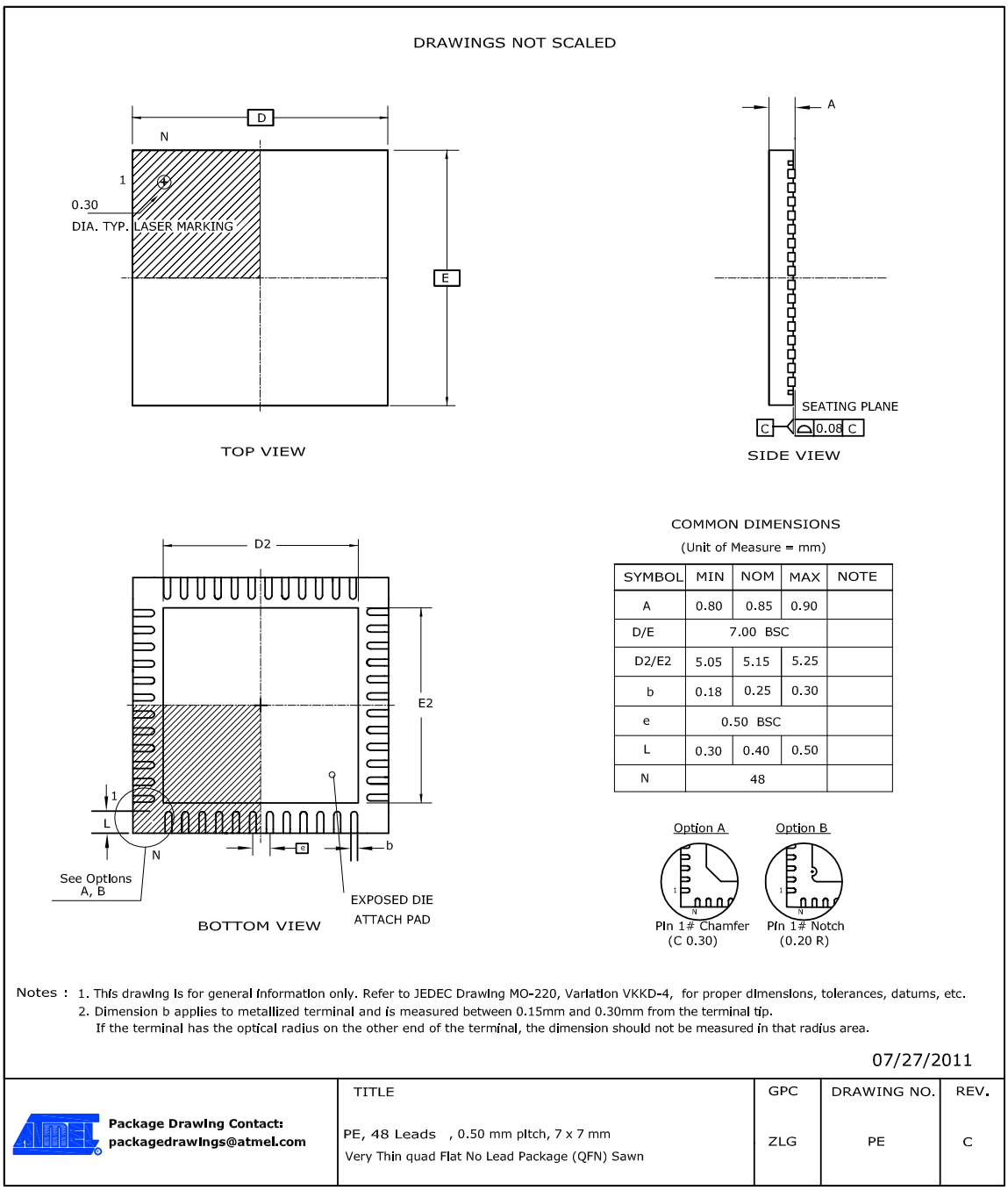
Table 12-15. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-16. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

12.2.6. 48 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 12-17. Device and Package Maximum Weight

140	mg

Table 12-18. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

12.3. Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Table 12-20.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.

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